Product / Package Information

Package	TQFP_EP
Body Size (mm)	10 X 10 X 1.0 (6.64 EP)
Lead Count	64
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.22E-01	88	880000	41.26	412624
Thermosets	Epoxy & Phenol resin	Proprietary	1.59E-02	11.5	115000	5.39	53922
Other inorganic materials	Carbon black	1333-86-4	6.91E-04	0.5	5000	0.23	2344
Subtotal			1.38 E-01	100.00	1000000	46.89	468891

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.20E-01	97.50	975000	40.74	407415
Copper & its alloys	Iron	7439-89-6	2.90E-03	2.35	23500	0.98	9820
Copper & its alloys	Zinc	7440-66-6	1.48E-04	0.12	1200	0.05	501
Copper & its alloys	Phosphorus	7723-14-0	3.70E-05	0.03	300	0.01	125
Subtotal			1.23 E-01	100.00	1000000	41.79	417862

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Silver	7440-22-4	5.70 E-04	100.0	1000000	0.19	1933

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	5.99 E-03	100.0	1000000	2.03	20310

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Gold	7440-57-5	1.07 E-03	100.00	1000000	0.36	3628

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.25 E-02	100.0	1000000	7.64	76391

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.38E-03	73.54	735400	0.81	8079
Other organic materials	Epoxy resin A	TS ref# 10013	2.38E-04	7.35	73500	0.08	807
Others	Anhydride	TS ref# 10181	2.38E-04	7.35	73500	0.08	807
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	9.53E-05	2.94	29400	0.03	323
Other organic materials	Epoxy resin B	TS ref# 10237	9.53E-05	2.94	29400	0.03	323
Others	Epoxy resin modifier	TS ref# 10038	9.53E-05	2.94	29400	0.03	323
Others	Anhydride	TS ref# 10180	9.53E-05	2.94	29400	0.03	323
Subtotal	Subtotal		3.24 E-03	100.00	1000000	1.10	10986

	Weight (g)	Percentage (%)	PPM
Package Totals	**2.95 E-01**	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary